

Applicant: Paolo Bellini et al.  
Appl. No.: 10/559,936

**AMENDMENTS TO THE SPECIFICATION**

Please replace paragraph 00<sup>42</sup>45 of the present application with the following amended paragraph 0045:

cb  
3.6.08

[0045] For better protection of the thick film circuit, the electronic components (46), the bonding wires (22) and the piezoresistors of the die (11), they may be coated with a layer of silicone resin (42) which, being elastic, is capable of following the deformations of the membrane (14), and does not therefore influence the pressure measurement effected by the die (11).